

Orbotech Corus™ 8M

Double-sided Imaging. Maximum Performance.



Orbotech Corus 8M is a fully automated direct imaging solution that replaces a complete DI line. Designed for Advanced HDI (including, mSAP) and IC substrate mass production, this integrated solution enables super-fine lines and outstanding accuracy, creating new opportunities for PCB manufacturers and designers.

Orbotech Corus leverages new and field-proven technologies for exceptionally high capacity and yield. This smart solution is compact, closed and clean, guaranteeing cutting-edge performance and eco-friendly manufacturing.



GO GREEN

Benefits

Fully Integrated Inline Solution

- Fully automated, double-sided imaging solution that replaces a complete DI line
- Unique optics and an ultra-powerful, multi-wave laser system for extremely high speed imaging
- Innovative panel handling and cleanliness mechanisms

Outstanding Resolution and Accuracy

- Super-fine, highly uniform line structure
- Exceptional positioning accuracy enabled by high precision design and advanced scaling algorithms
- High depth-of-focus (DOF) for best line quality on varying surface topographies

Smart Operation

- High-speed, multi-target acquisition for any layout, ensuring high productivity
- Intelligent job queue management to streamline workflow processes
- Supports Industry 4.0 for advanced traceability and process optimization

Reduced TCO

- High throughput achieved by a combination of large scan optics, on-the-fly target recognition and efficient automation
- Small footprint for maximum capacity per m², occupying less clean room
- Highly efficient power consumption

Technologies



DSI™ Technology

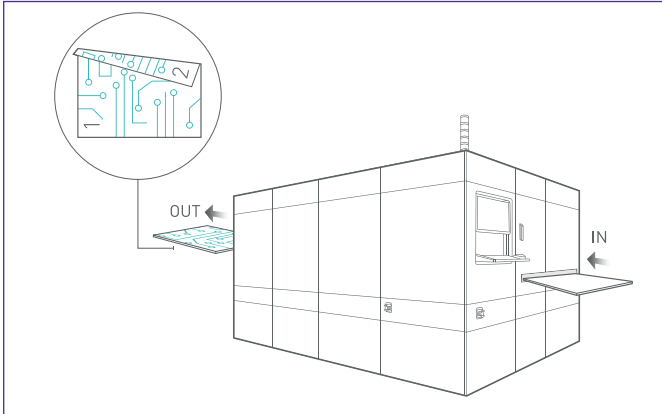


LSO™ Technology



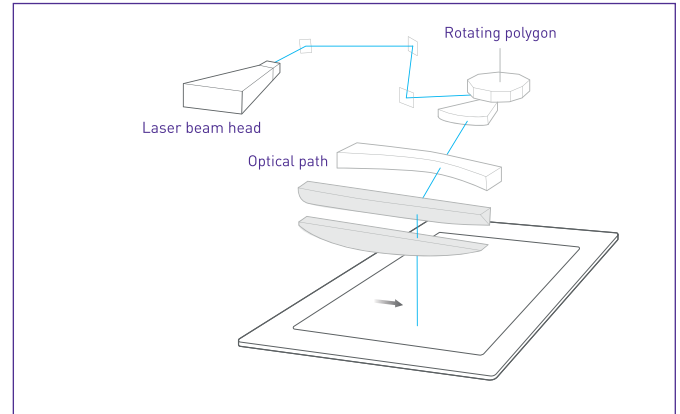
MultiWave Laser™ Technology

Fully Automated, Double-Sided DI



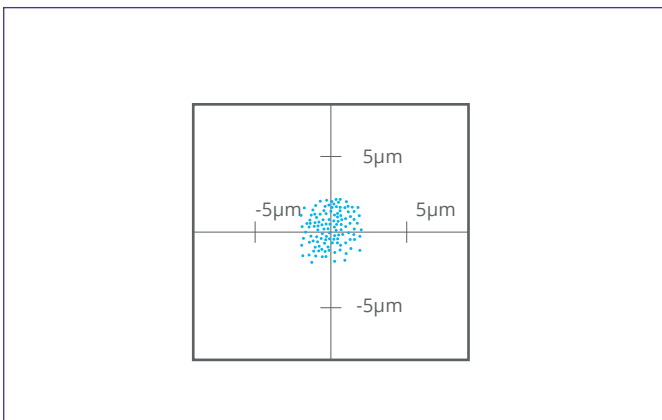
Fully automated, double-sided DI solution to maximize capacity and yield for high-volume production

Superior Line Quality



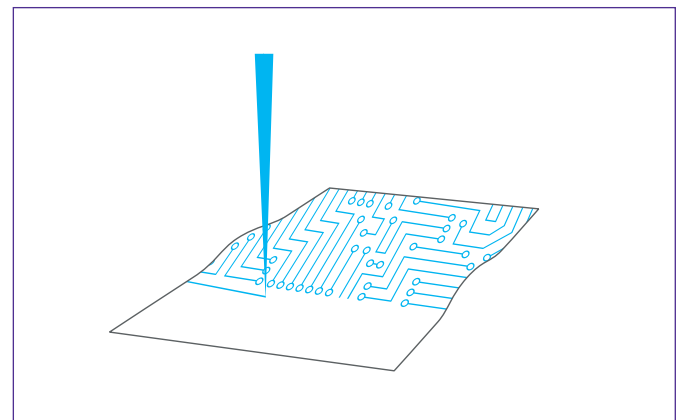
Super-fine line structure in a single scan enabled by KLA's field-proven LSO™ Technology

Outstanding Accuracy



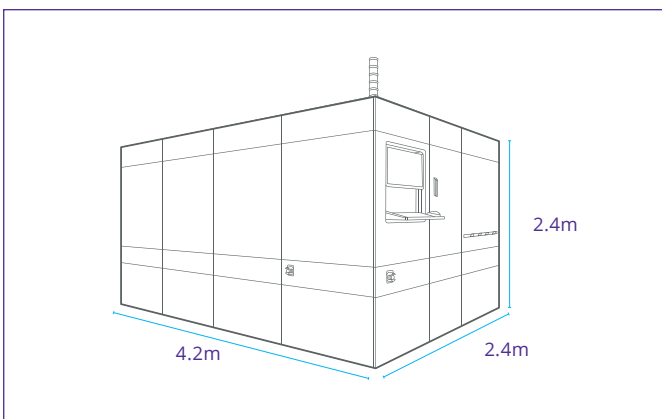
Registration accuracy as fine as $\pm 5\mu\text{m}$ for advanced applications

High Depth-of-Focus (DOF)



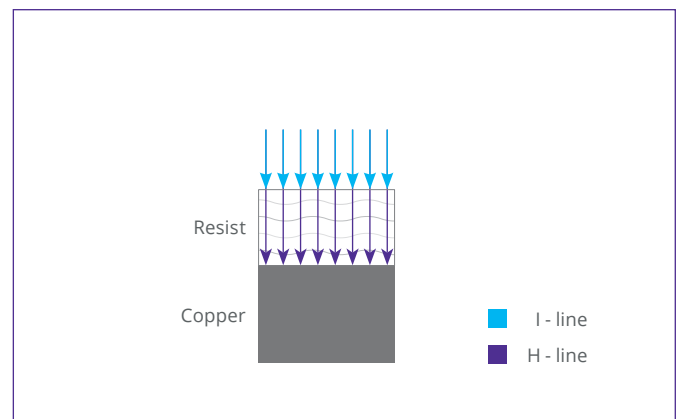
High depth-of-focus (DOF) for best line precision and uniformity on varying surface topographies

All-in-one, Compact Design



Fully integrated solution in a closed, compact box for maximum cleanliness and efficiency

Maximum Resist Flexibility



Compatible with a wide range of resists and processes, driven by KLA's field-proven MultiWave Laser™ technology

Specifications

Orbotech Corus 8M

Minimum Line Width*	8μm
Minimum Pitch*	20μm
Edge Roughness, 3σ	±1μm
Registration Accuracy (FTG), 3σ	±5μm
Registration Accuracy (FTB), 3σ	10μm
Maximum Substrate Size	660mm x 660mm (26" x 26")
Maximum Exposure Size	635mm x 660mm (25" x 26")
Dimensions (l) x (w) x (h)	4.2m x 2.4m x 2.4m

* Dependent on resist type and processes

KLA SUPPORT

Maintaining system productivity is an integral part of KLA's yield optimization solution. Efforts in this area include system maintenance, global supply chain management, cost reduction and obsolescence mitigation, system relocation, performance and productivity enhancements, and certified tool resale.

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